



AOS
SEMICONDUCTOR

产品规格说明书

Product Data Sheet

AOS631B XK-G

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电源管理IC



通信接口芯片



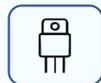
二三极管



LDO稳压器



逻辑器件



MOSFETs



运算放大器



显示驱动



MCU单片机



光电器件



Low Drift, Low Power Instrumentation Amplifier

DESCRIPTIONS

The AOS631B device is a low-power, precision instrumentation amplifier offering excellent accuracy. The versatile 3-operational amplifier design, small size, and low power make it ideal for a wide range of portable applications.

Provides multiple fixed gain configurations.

The AOS631B device provides very low offset voltage ($\pm 70\mu V$), and high common-mode rejection (110dB). It operates with power supplies as low as 4.6V ($\pm 2.3V$) and quiescent current is only 3.4mA, making it ideal for battery operated systems. Using autocalibration

techniques to ensure excellent precision over the extended industrial temperature range.

The AOS631B device is available in SOP8 packages. It operates over an ambient temperature range of $-40^{\circ}C$ to $+125^{\circ}C$.

FEATURES

- Fixed Gain: 10
- Low Offset Voltage: $\pm 70\mu V$ (TYP)
- High CMRR: 110dB (TYP)
- Low Input Bias Current: 0.5nA (TYP)
- Supply Range: $\pm 2.3 V$ to $\pm 16 V$
- Input Voltage: $(V-)+0.6V$ to $(V+)-1.5V$
- Low Quiescent Current: 3.4mA
- Operating Temperature: $-40^{\circ}C$ to $+125^{\circ}C$
- Micro Size Packages: SOP8

APPLICATIONS

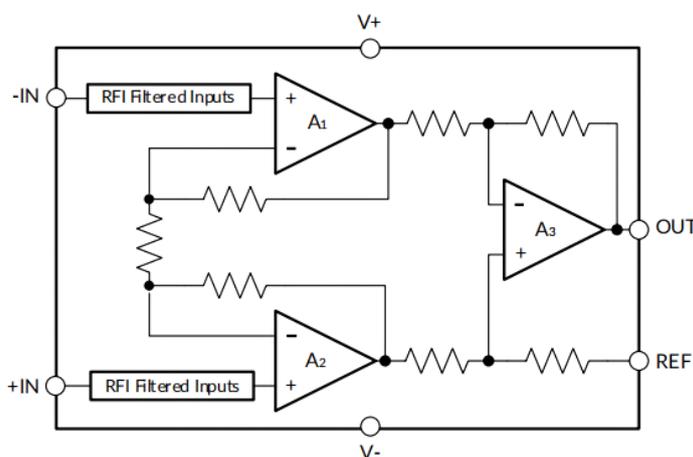
- Weigh Scales
- Transducer Interface and Data Acquisition Systems
- Industrial Process Controls
- Battery-Powered and Portable Equipment

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)
AOS631B	SOP8	4.90mm x 3.90mm

(1)For all available packages, see the orderable addendum at the end of the data sheet.

Simplified Schematic





PACKAGE/ORDERING INFORMATION⁽¹⁾

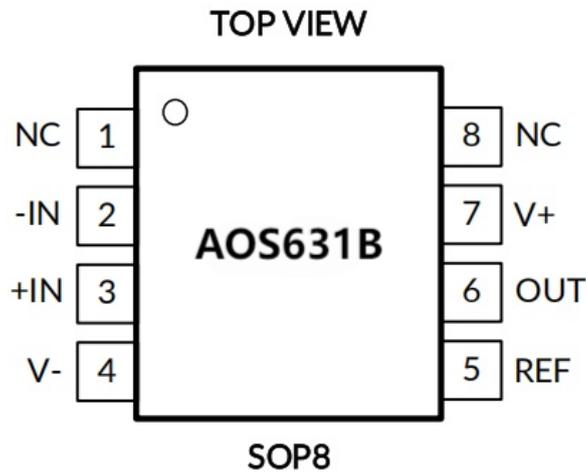
PRODUCT	ORDERING NUMBER	TEMPERATURE RANGE	PACKAGE LEAD	PACKAGE MARKING ⁽²⁾	MSL ⁽³⁾	PACKAGE OPTION
AOS631B	AOS631BXK-G	-40°C ~125°C	SOP8	AOS631B	MSL1	Tape and Reel , 4000

NOTE:

- (1) This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the right-hand navigation.
- (2) There may be additional marking, which relates to the lot trace code information (data code and vendor code), the logo or the environmental category on the device.
- (3) MSL, The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications.



PIN CONFIGURATION AND FUNCTIONS



PIN DESCRIPTION

PIN	NAME	I/O ⁽¹⁾	DESCRIPTION
SOP8			
1	NC ⁽²⁾	-	No internal connection (can be left floating)
2	-IN	I	Inverting input
3	+IN	I	Noninverting input
4	V-	-	Negative (lowest) power supply
5	REF	I	Reference input
6	OUT	O	Output
7	V+	-	Positive (highest) power supply
8	NC ⁽²⁾	-	No internal connection (can be left floating)

(1) I = Input, O = Output.

(2) There is no internal connection. Typically, GND is the recommended connection to a heat spreading plane.



Specifications

Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
Voltage	Supply Voltage		34	V
	Analog input voltage ⁽²⁾	(V-)-0.3	(V+)+0.3	
Current	Signal input pin ⁽²⁾	-10	10	mA
	Signal output pin ⁽³⁾	-10	10	mA
	Output short-circuit ⁽⁴⁾	Continuous		
J _A	Package thermal impedance ⁽⁵⁾	SOP8	110	°C/W
Temperature	Operating range, T _A	-40	125	°C
	Junction, T _J ⁽⁶⁾	-40	150	
	Storage, T _{stg}	-65	150	

- (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.
- (2) Input terminals are diode-clamped to the power-supply rails. Input signals that can swing more than 0.5V beyond the supply rails should be current-limited to 10mA or less.
- (3) Output terminals are diode-clamped to the power-supply rails. Output signals that can swing more than 0.5V beyond the supply rails should be current-limited to ± 100 mA or less.
- (4) Short-circuit to ground, one amplifier per package.
- (5) The package thermal impedance is calculated in accordance with JESD-51.
- (6) The maximum power dissipation is a function of T_{J(MAX)}, R_{J A}, and T_A. The maximum allowable power dissipation at any ambient temperature is $P_D = (T_{J(MAX)} - T_A) / R_{J A}$. All numbers apply for packages soldered directly onto a PCB.



ESD Ratings

The following ESD information is provided for handling of ESD-sensitive devices in an ESD protected area only.

			VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human-body model (HBM)	± 2000	V
		Machine Model (MM)	± 1500	



ESD SENSITIVITY CAUTION

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

Recommended Operating Conditions

Over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
Supply voltage	Single-supply	4.6		32	V
	Dual-supply	± 2.3		± 16	
Specified temperature		-40		125	°C



ELECTRICAL CHARACTERISTICS

Gain=10, $V_s = \pm 15V$, $T_A = 25^\circ C$ (unless otherwise noted.)⁽¹⁾

PARAMETER	CONDITIONS	AOS631B			UNITS
		MIN	TYP	MAX	
GAIN					
Gain Error	$V_{OUT} = \pm 10 V$		0.21	0.6	%
Nonlinearity, $V_{OUT} = -10 V$ to $+10 V$			30		ppm of FS
Gain vs Temperature			18		ppm/ $^\circ C$
TOTAL VOLTAGE OFFSET					
Offset (RTI) ⁽⁴⁾	$V_s = \pm 16 V$	-150	± 70	150	μV
Average TC			10		$\mu V/^\circ C$
Offset Referred to the Input vs Supply (PSR)	$V_s = \pm 2.3 V$ to $\pm 16 V$	95	115		dB
Total NOISE					
Voltage Noise (RTI)	0.1 Hz to 10 Hz		1.45		$\mu Vp-p$
INPUT CURRENT					
Input Bias Current ⁽⁵⁾⁽⁶⁾	$V_s = \pm 15V$	-3	0.5	3	nA
Over Temperature ⁽⁵⁾		-5		5	nA
Input Offset Current ⁽⁵⁾		-1		1	nA
Over Temperature ⁽⁵⁾		-1.5		1.5	nA
INPUT					
Input Impedance					
Differential			10 2		G pF
Common-Mode			10 2		G pF
Common-Mode RejectionRatio	$(V_-)+0.6V < V_{CM} < (V_+)-1.5V$	90	110		dB



OUTPUT					
Output Swing	$R_L = 10k$, $V_S = \pm 2.3V$ to $\pm 5V$	$-V_S + 0.15$		$+V_S - 0.15$	V
	$R_L = 10k$, $V_S = \pm 5V$ to $\pm 15V$	$-V_S + 0.35$		$+V_S - 0.35$	V
Short Current Circuit ⁽⁷⁾⁽⁸⁾		± 70	± 80		mA
DYNAMIC RESPONSE					
Small Signal, -3 dB Bandwidth			900		kHz
Slew Rate ⁽⁹⁾			1.1		V/ μ s
Settling Time	10 V Step		20		μ s
REFERENCE INPUT					
RIN			20		k
Voltage Range		-VS		+VS	V
POWER SUPPLY					
Operating Range		± 2.3		± 16	V
Quiescent Current	$V_S = \pm 2.3 V$ to $\pm 16 V$		3.4	4.5	mA
TEMPERATURE RANGE					
For Specified Performance		-40		125	$^{\circ}C$

NOTE:

- (1) Electrical table values apply only for factory testing conditions at the temperature indicated. Factory testing conditions result in very limited self-heating of the device.
- (2) Limits are 100% production tested at 25°C. Limits over the operating temperature range are ensured through correlations using statistical quality control (SQC) method.
- (3) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration.
- (4) RTI = Referred-to-input.
- (5) This parameter is ensured by design and/or characterization and is not tested in production.
- (6) Positive current corresponds to current flowing into the device.
- (7) The maximum power dissipation is a function of $T_{J(MAX)}$, R_{JA} , and T_A . The maximum allowable power dissipation at any ambient temperature is $P_D = (T_{J(MAX)} - T_A) / R_{JA}$. All numbers apply for packages soldered directly onto a PCB.
- (8) Short circuit test is a momentary test.
- (9) Number specified is the slower of positive and negative slew rates.



TYPICAL CHARACTERISTICS

NOTE: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only.

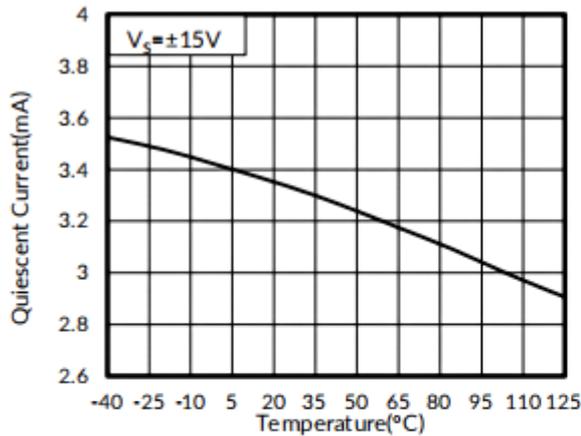


Figure 1. Quiescent Current vs Temperature

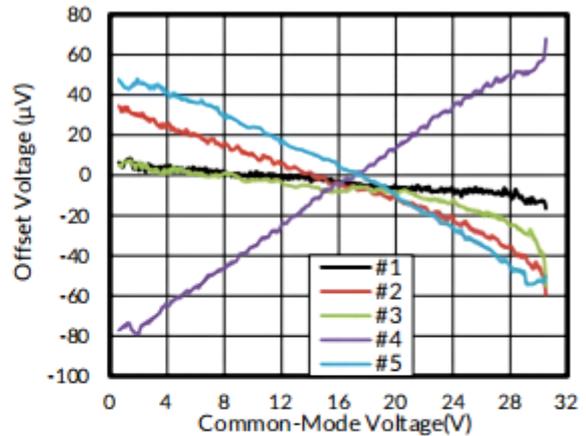


Figure 2. Offset Voltage vs Common-Mode Voltage

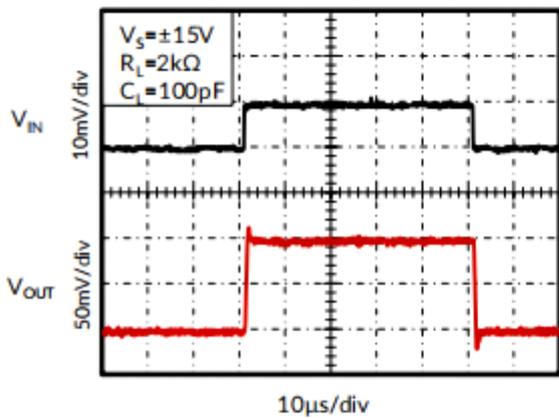


Figure 3. Small Signal Pulse Response

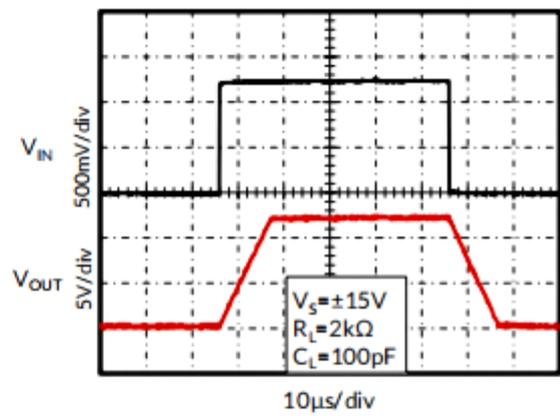


Figure 4. Large Signal Pulse Response

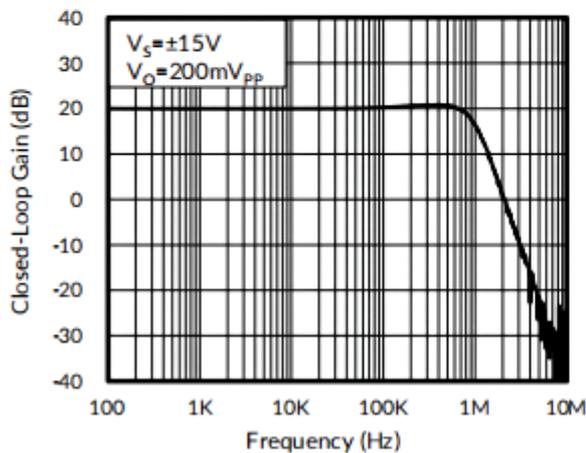


Figure 5. Closed-Loop Gain vs Frequency

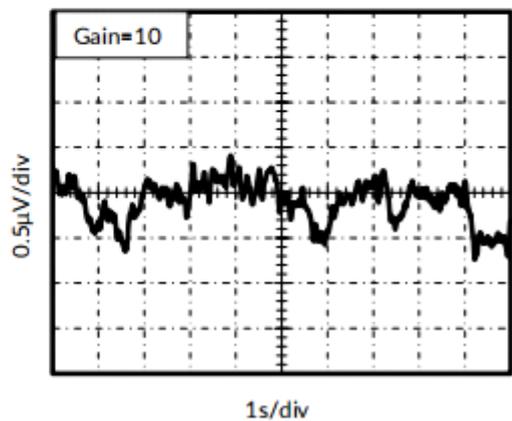


Figure 6. 0.1Hz to 10Hz RTI Voltage Noise



Application and Implementation

Information in the following applications sections is not part of the AOS component specification, and AOS does not warrant its accuracy or completeness. AOS's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

Ground Returns for Input Bias Currents

Input bias currents are those currents necessary to bias the input transistors of an amplifier. There must be a direct return path for these currents; therefore when amplifying “floating” input sources such as transformers, or ac-coupled sources, there must be a dc path from each input to ground as shown in Figures 7 through 9.

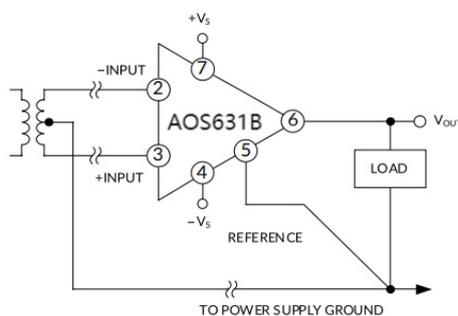


Figure 7. Ground Returns for Bias Currents when Using Transformer Input Coupling

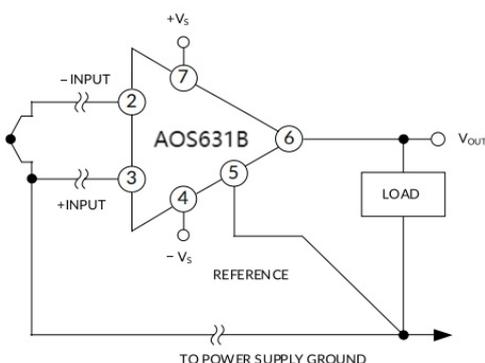


Figure 8. Ground Returns for Bias Currents when Using a Thermocouple Input

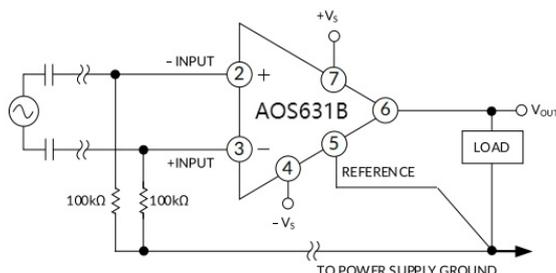
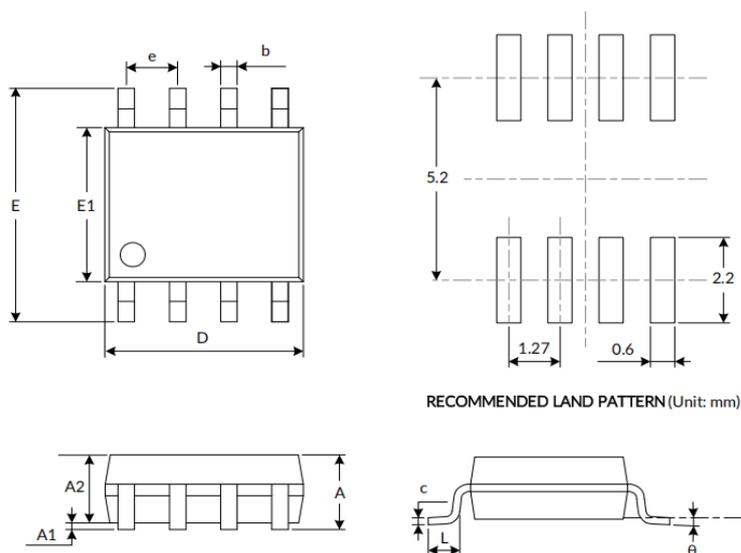


Figure 9. Ground Returns for Bias Currents when Using AC Input Coupling



PACKAGE OUTLINE DIMENSIONS
SOP8⁽³⁾



RECOMMENDED LAND PATTERN (Unit: mm)

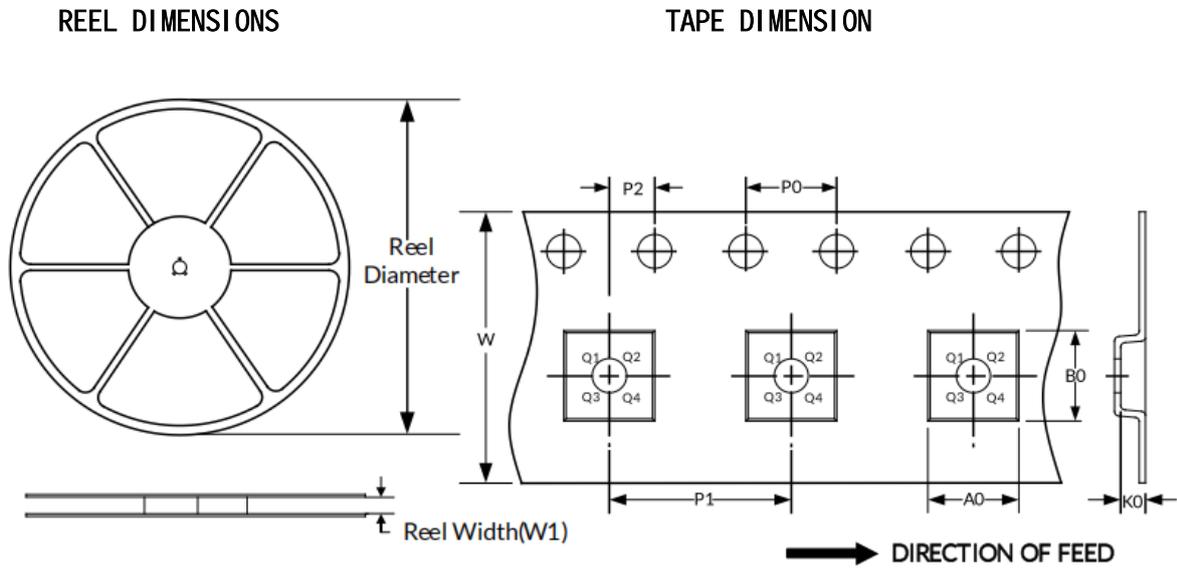
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A ⁽¹⁾	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D ⁽¹⁾	4.800	5.000	0.189	0.197
e	1.270(BSC) ⁽²⁾		0.050(BSC) ⁽²⁾	
E	5.800	6.200	0.228	0.244
E1 ⁽¹⁾	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
	0°	8°	0°	8°

NOTE:

1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.



TAPE AND REEL INFORMATION



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width(mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
SOP8	13''	12.4	6.40	5.40	2.10	4.0	8.0	2.0	12.0	Q1

NOTE:

1. All dimensions are nominal.
2. Plastic or metal protrusions of 0.15mm maximum per side are not included.